

300mm Fully-Automatic BG Tape Remover

# RAD-3010F/12



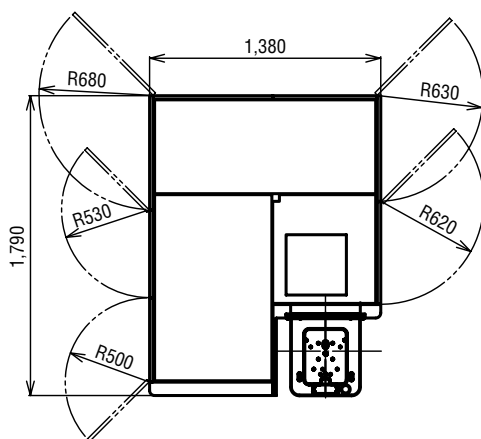
## Outline

- Fully-automatic BG Tape remover for single wafer.
- After alignment, UV is irradiated when necessary, and back grinding tape is removed by attaching heat seal on the periphery of the wafer, fixed with heater.

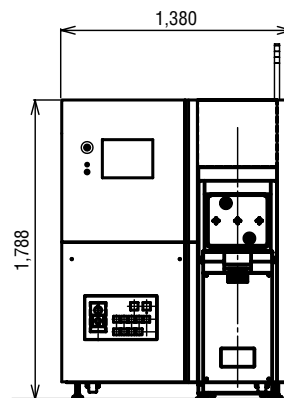
**Options** ·Host Communication Function (Communication Format :  
Conforms to SECS-I and HSMS/Software : Conforms to GEM)  
·Barcode Reader for Selecting Recipes

**Suitable Tapes** ·BG Tape : Adwill E series, P series

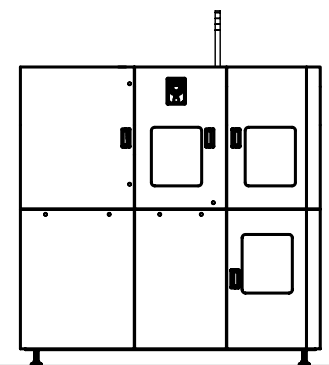
## External View



Top View



Front View



Left Side View

Unit:mm

## Facility

<b>Power Supply</b>	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
<b>Air Supply</b>	Capacity	: 5.0kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)
<b>Vacuum Supply</b>	Vacuum pressure	: >-80kPa

**Applicable Wafer Size** 200mm, 300mm

**Size** Width : 1,380mm  
Depth : 1,790mm  
Height : 1,788mm  
(excluding the signal tower)

**Weight** 1,100kg

**UPH** 65wafers/hour

The above processing capacity is based on following conditions:

Wafer : 300mm diameter non-polished mirror wafer  
Back grinding tape : E-6152 from LINTEC



**LINTEC Corporation** *Linking your dreams*

●Head Office:23-23 Honcho, Itabashi-ku, Tokyo 173-0001, Japan

Contact:Advanced Materials Operations Kowa Iidabashi Bldg., 2-1-2 Koraku, Bunkyo-ku,  
Tokyo 112-0004, Japan  
TEL. +81-3-3868-7737 FAX. +81-3-3868-7726  
E-mail:adwill@lintec.co.jp

<http://www.lintec-global.com/>